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OptiMOS[®] -P2 Power-Transistor



Product Summary

| | | |
|----------------------------|-----|------------|
| V_{DS} | -30 | V |
| $R_{DS(on)}$ (SMD Version) | 6.9 | m Ω |
| I_D | -80 | A |

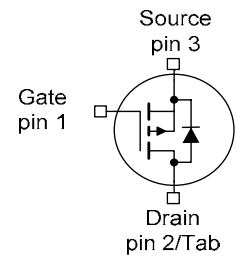
Features

- P-channel - Logic Level - Enhancement mode
- AEC qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (RoHS compliant)
- 100% Avalanche tested
- Intended for reverse battery protection

PG-TO263-3-2 PG-TO262-3-1 PG-TO220-3-1



| Type | Package | Marking |
|----------------|--------------|---------|
| IPB80P03P4L-07 | PG-TO263-3-2 | 4P03L07 |
| IPI80P03P4L-07 | PG-TO262-3-1 | 4P03L07 |
| IPP80P03P4L-07 | PG-TO220-3-1 | 4P03L07 |



Maximum ratings, at $T_j=25\text{ }^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Conditions | Value | Unit |
|-------------------------------------|----------------|---|--------------|------------------|
| Continuous drain current | I_D | $T_C=25\text{ }^\circ\text{C}$, $V_{GS}=-10\text{V}^{(1)}$ | -80 | A |
| | | $T_C=100\text{ }^\circ\text{C}$, $V_{GS}=-10\text{V}^{(2)}$ | -65 | |
| Pulsed drain current ²⁾ | $I_{D,pulse}$ | $T_C=25\text{ }^\circ\text{C}$ | -320 | |
| Avalanche energy, single pulse | E_{AS} | $I_D=-40\text{A}$ | 135 | mJ |
| Avalanche current, single pulse | I_{AS} | - | -80 | A |
| Gate source voltage | V_{GS} | - | +5/-16 | V |
| Power dissipation | P_{tot} | $T_C=25\text{ }^\circ\text{C}$ | 88 | W |
| Operating and storage temperature | T_j, T_{stg} | - | -55 ... +175 | $^\circ\text{C}$ |
| IEC climatic category; DIN IEC 68-1 | - | - | 55/175/56 | |

| Parameter | Symbol | Conditions | Values | | | Unit |
|--|------------|--|--------|------|------|------|
| | | | min. | typ. | max. | |
| Thermal characteristics²⁾ | | | | | | |
| Thermal resistance, junction - case | R_{thJC} | - | - | - | 1.7 | K/W |
| Thermal resistance, junction - ambient, leaded | R_{thJA} | - | - | - | 62 | |
| SMD version, device on PCB | R_{thJA} | minimal footprint | - | - | 62 | |
| | | 6 cm ² cooling area ³⁾ | - | - | 40 | |

Electrical characteristics, at $T_j=25^\circ\text{C}$, unless otherwise specified

Static characteristics

| | | | | | | |
|----------------------------------|---------------|--|------|-------|------|------------|
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=-1mA$ | -30 | - | - | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-130\mu A$ | -1.0 | -1.5 | -2.0 | |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=-24V, V_{GS}=0V, T_j=25^\circ\text{C}$ | - | -0.03 | -1 | μA |
| | | $V_{DS}=-24V, V_{GS}=0V, T_j=125^\circ\text{C}^{2)}$ | - | -10 | -100 | |
| Gate-source leakage current | I_{GSS} | $V_{GS}=-16V, V_{DS}=0V$ | - | - | -100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=-4.5V, I_D=-40A$ | - | 8.3 | 12.3 | m Ω |
| | | $V_{GS}=-4.5V, I_D=-40A, \text{SMD version}$ | - | 8.0 | 12 | |
| | | $V_{GS}=-10V, I_D=-80A$ | - | 5.9 | 7.2 | |
| | | $V_{GS}=-10V, I_D=-80A, \text{SMD version}$ | - | 5.6 | 6.9 | |

| Parameter | Symbol | Conditions | Values | | | Unit |
|-----------|--------|------------|--------|------|------|------|
| | | | min. | typ. | max. | |

Dynamic characteristics²⁾

| | | | | | | |
|------------------------------|--------------|---|---|------|------|----|
| Input capacitance | C_{iss} | $V_{GS}=0V, V_{DS}=-25V,$ $f=1MHz$ | - | 4400 | 5700 | pF |
| Output capacitance | C_{oss} | | - | 1220 | 1600 | |
| Reverse transfer capacitance | C_{rss} | | - | 30 | 60 | |
| Turn-on delay time | $t_{d(on)}$ | $V_{DD}=-15V,$ $V_{GS}=-10V, I_D=-80A,$ $R_G=3.5\Omega$ | - | 8 | - | ns |
| Rise time | t_r | | - | 4 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 15 | - | |
| Fall time | t_f | | - | 60 | - | |

Gate Charge Characteristics²⁾

| | | | | | | |
|-----------------------|---------------|--|---|------|----|----|
| Gate to source charge | Q_{gs} | $V_{DD}=-24V, I_D=-80A,$ $V_{GS}=0$ to $-10V$ | - | 16 | 20 | nC |
| Gate to drain charge | Q_{gd} | | - | 8 | 16 | |
| Gate charge total | Q_g | | - | 63 | 80 | |
| Gate plateau voltage | $V_{plateau}$ | | - | -3.7 | - | V |

Reverse Diode

| | | | | | | |
|--|---------------|--|---|----|------|----|
| Diode continuous forward current ²⁾ | I_S | $T_C=25^\circ C$ | - | - | -80 | A |
| Diode pulse current ²⁾ | $I_{S,pulse}$ | | - | - | -320 | |
| Diode forward voltage | V_{SD} | $V_{GS}=0V, I_F=-80A,$ $T_j=25^\circ C$ | - | - | -1.3 | V |
| Reverse recovery time ²⁾ | t_{rr} | $V_R=-15V, I_F=-80A,$ $di_F/dt=-100A/\mu s$ | - | 50 | - | ns |
| Reverse recovery charge ²⁾ | Q_{rr} | | - | 40 | - | nC |

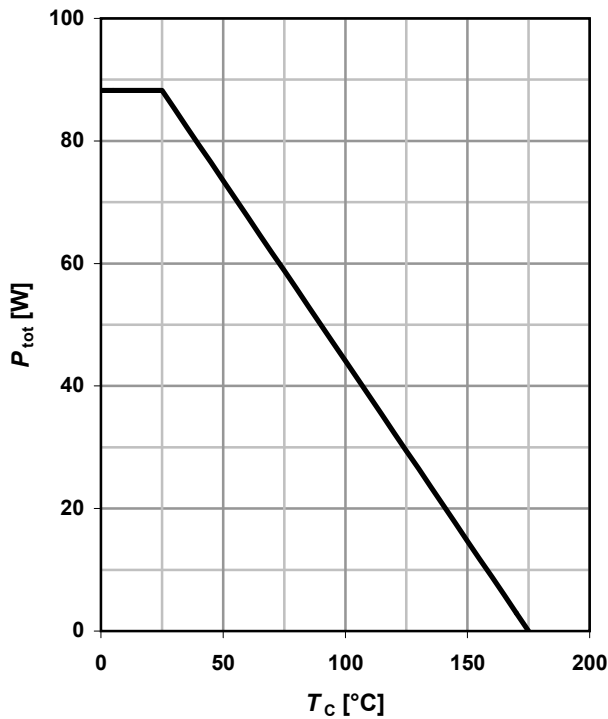
¹⁾ Current is limited by bondwire; with an $R_{thJC} = 1.7K/W$ the chip is able to carry 92A at 25°C.

²⁾ Defined by design. Not subject to production test.

³⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical in still air.

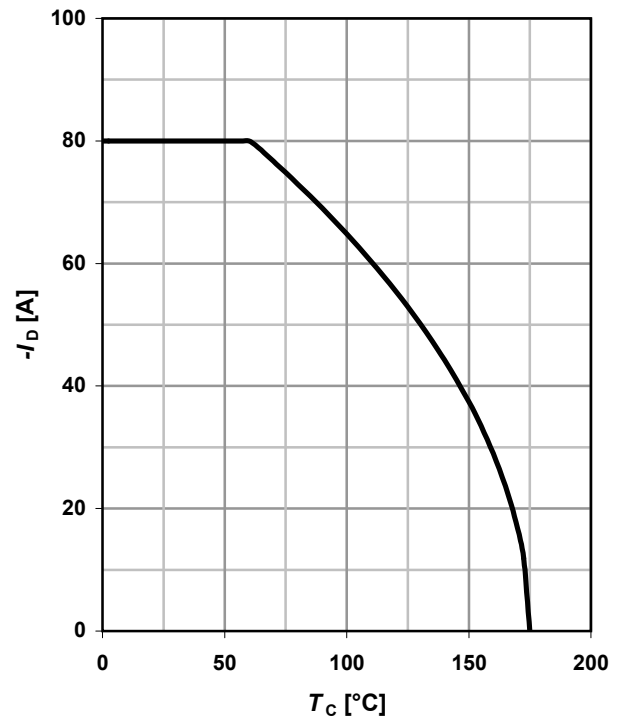
1 Power dissipation

$P_{tot} = f(T_C); V_{GS} \leq -6V$



2 Drain current

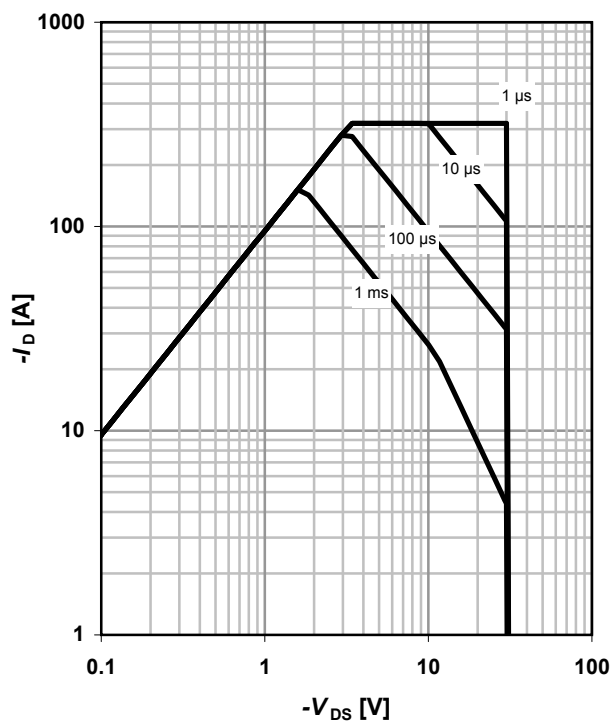
$I_D = f(T_C); V_{GS} \leq -6V; SMD$



3 Safe operating area

$I_D = f(V_{DS}); T_C = 25\text{ °C}; D = 0; SMD$

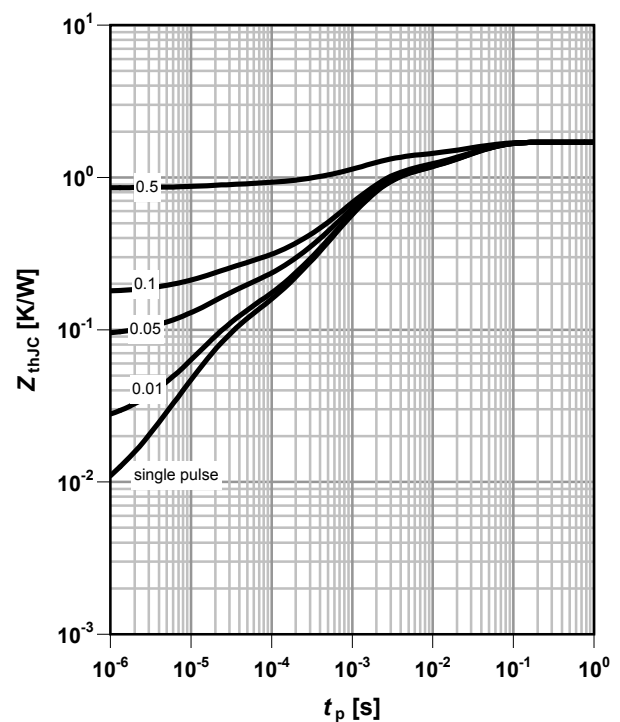
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

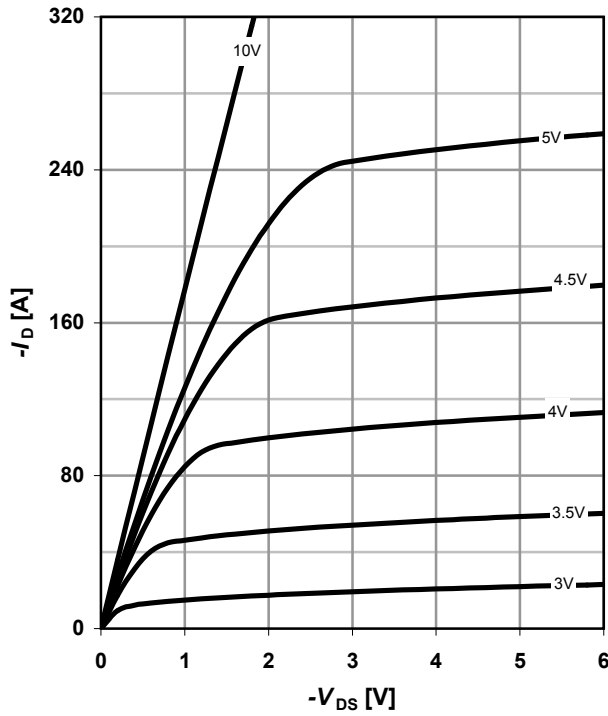
parameter: $D = t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25\text{ }^\circ\text{C}; \text{SMD}$

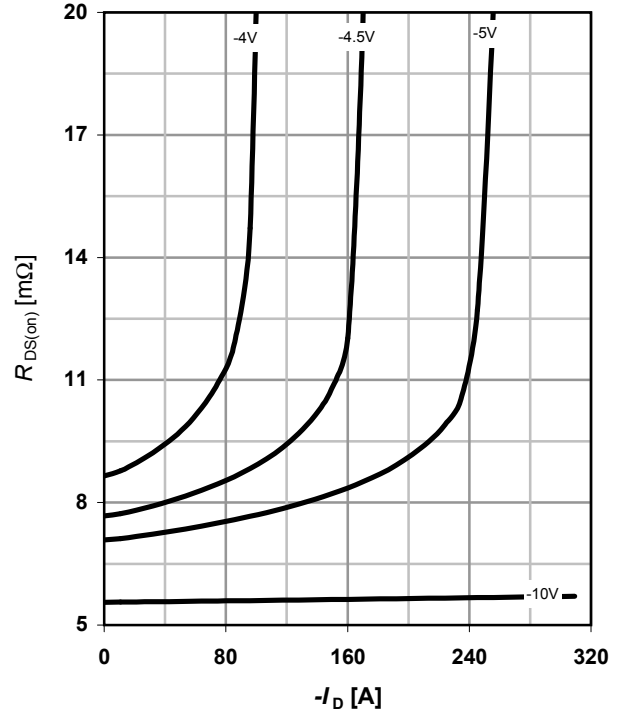
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D); T_j = 25\text{ }^\circ\text{C}; \text{SMD}$

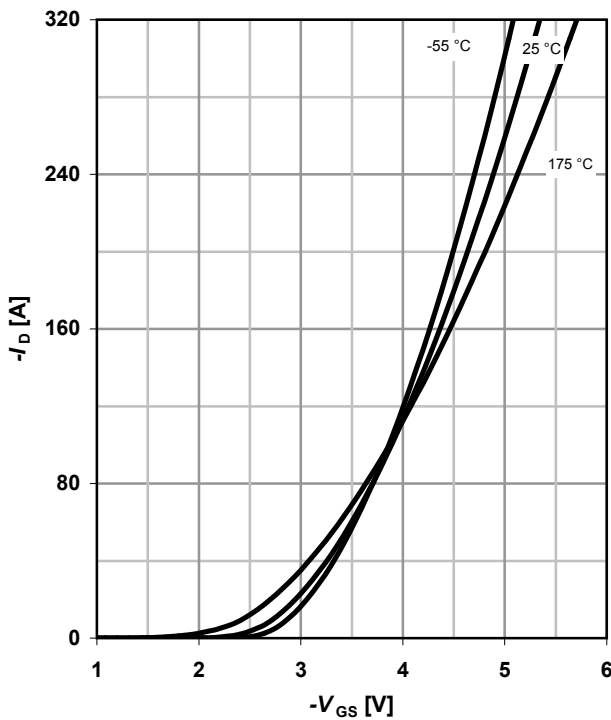
parameter: V_{GS}



7 Typ. transfer characteristics

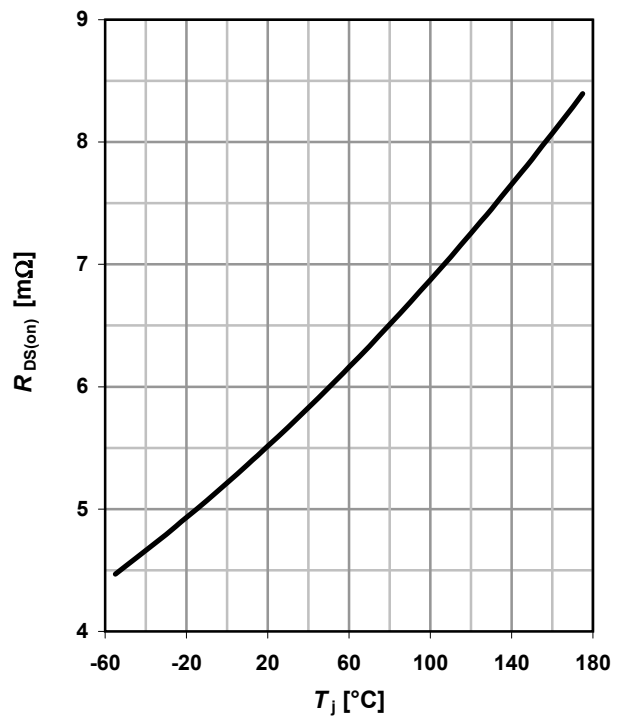
$I_D = f(V_{GS}); V_{DS} = -6\text{V}$

parameter: T_j



8 Typ. drain-source on-state resistance

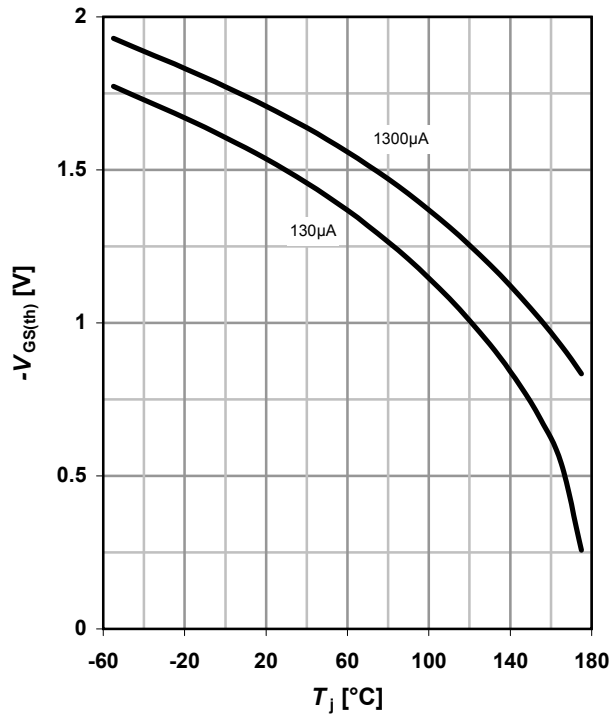
$R_{DS(on)} = f(T_j); I_D = -80\text{ A}; V_{GS} = -10\text{ V}; \text{SMD}$



9 Typ. gate threshold voltage

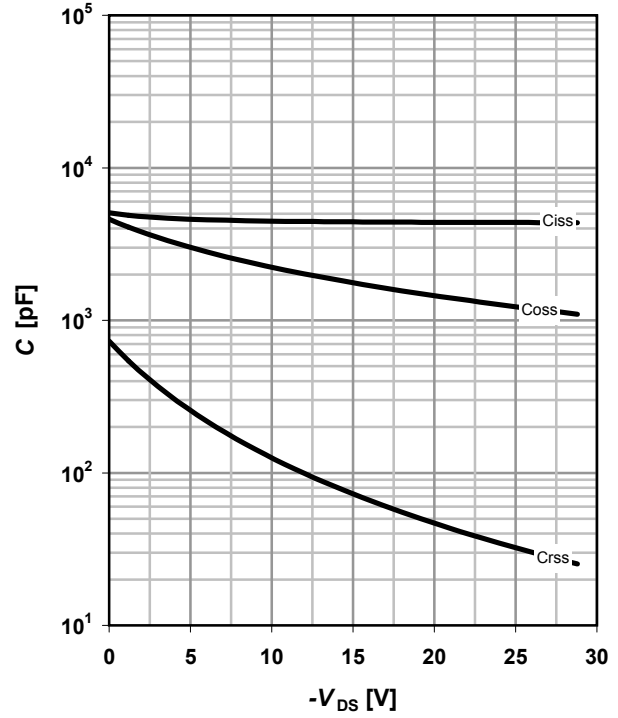
$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$

parameter: $-I_D$



10 Typ. capacitances

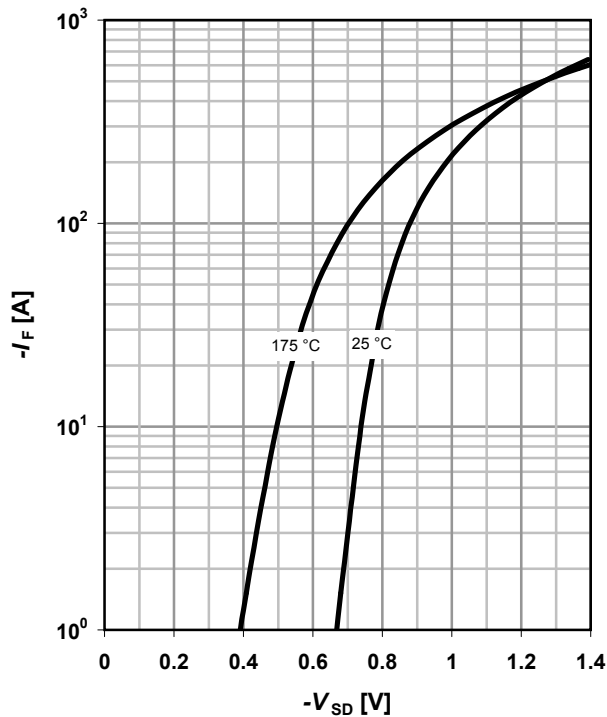
$C = f(V_{DS}); V_{GS} = 0 V; f = 1 MHz$



11 Typical forward diode characteristics

$I_F = f(V_{SD})$

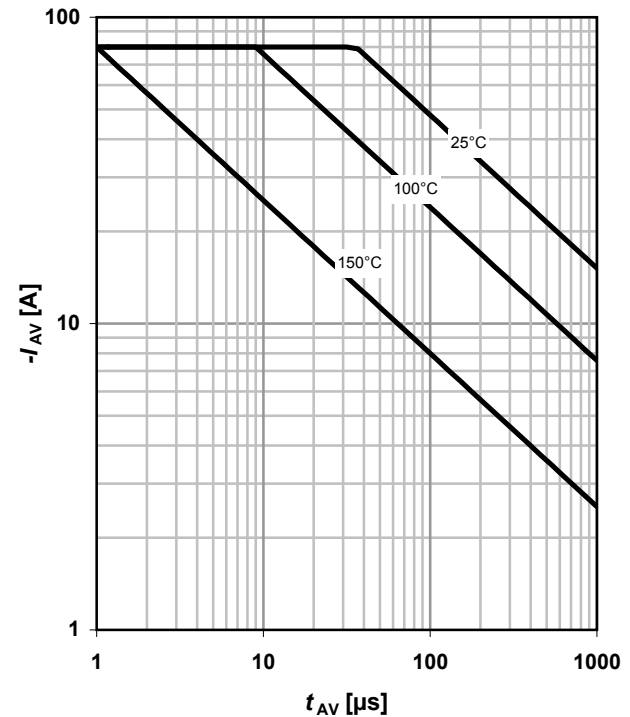
parameter: T_j



12 Avalanche characteristics

$I_{AS} = f(t_{AV})$

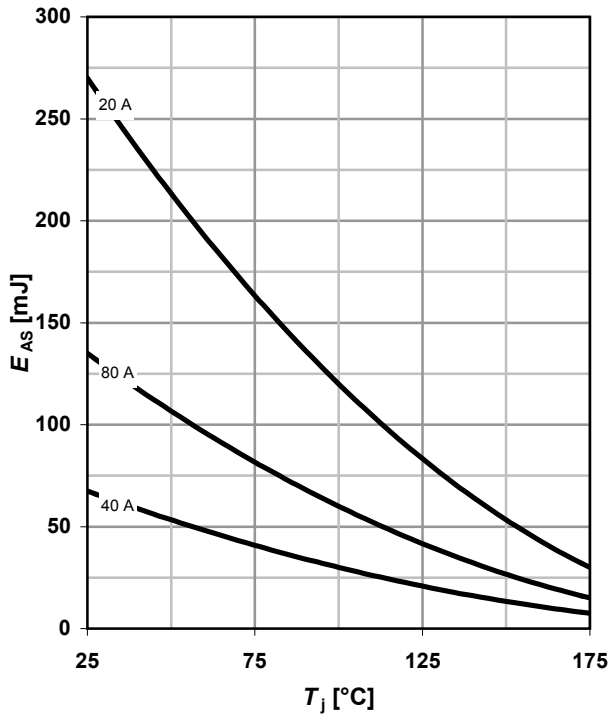
parameter: $T_{j(start)}$



13 Avalanche energy

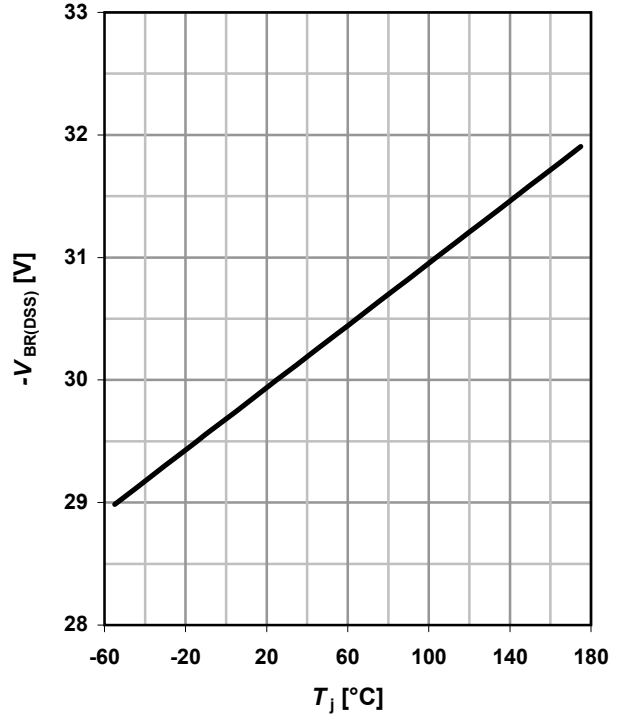
$$E_{AS} = f(T_j)$$

parameter: I_D



14 Drain-source breakdown voltage

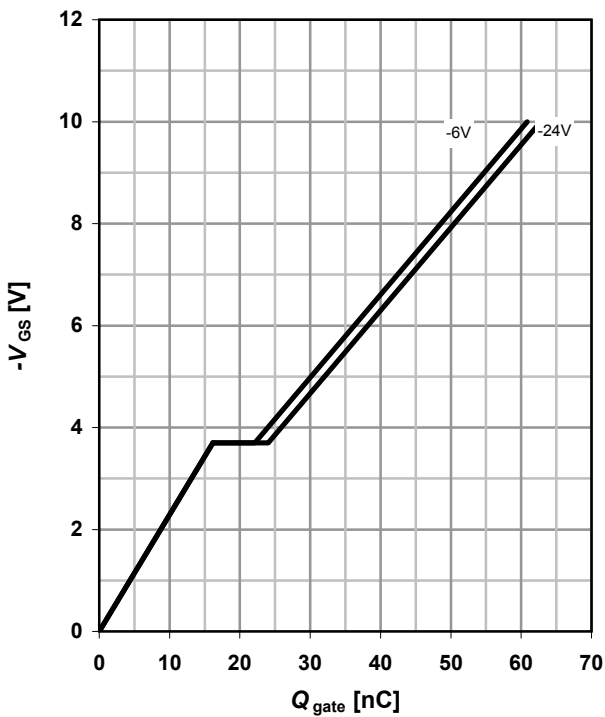
$$V_{BR(DSS)} = f(T_j); I_D = -1 \text{ mA}$$



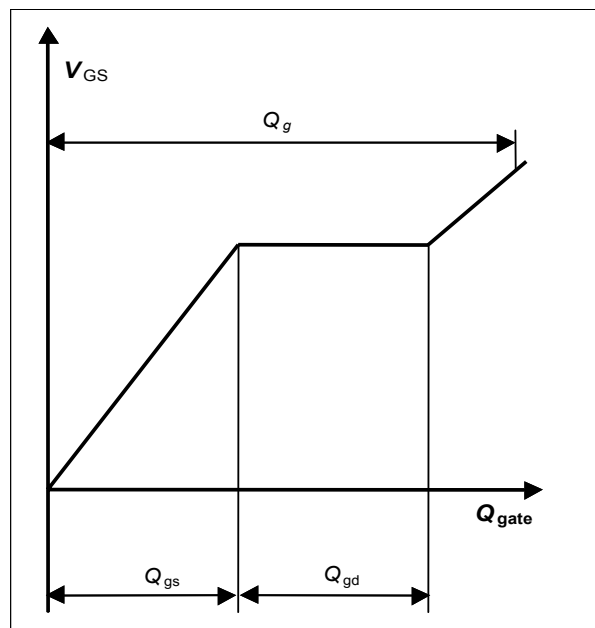
15 Typ. gate charge

$$V_{GS} = f(Q_{gate}); I_D = -80 \text{ A pulsed}$$

parameter: V_{DD}



16 Gate charge waveforms



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